

## Product Summary

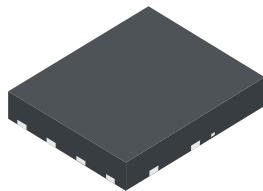
$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$ $T_A = 25^\circ\text{C}$ (Note 5)
-30V	7.5m $\Omega$ @ $V_{GS} = -10\text{V}$	-36A
	10m $\Omega$ @ $V_{GS} = -4.5\text{V}$	-31A

## Description

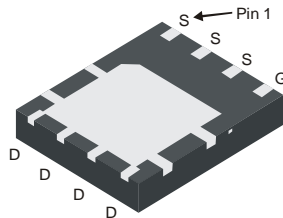
This new generation 30V P-Channel Enhancement Mode MOSFET has been designed to minimize  $R_{DS(on)}$  and yet maintain superior switching performance. This device is ideal for use in Notebook battery power management and Loadswitch.

## Applications

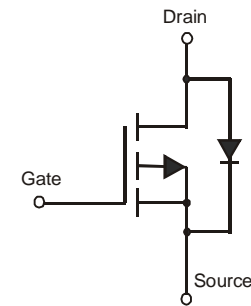
- Notebook Battery Power Management
- DC-DC Converters
- Loadswitch



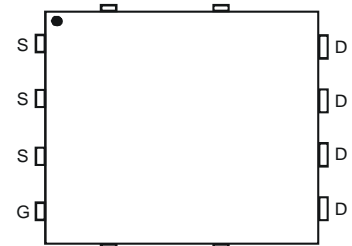
Top View



Bottom View



Internal Schematic



Top View  
Pin Configuration

## Features

- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low  $R_{DS(on)}$  – Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- <1.1mm Package Profile – Ideal for Thin Applications
- ESD HBM Protected up to 1kV
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

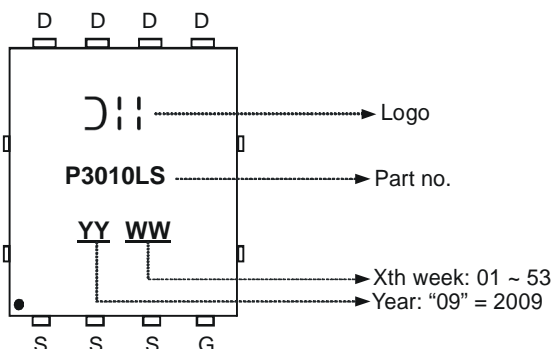
- Case: POWERDI5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.097 grams (approximate)

## Ordering Information (Note 4)

Part Number	Case	Packaging
DMP3010LPS-13	POWERDI5060-8	2500 / Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com>.

## Marking Information



**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	-30	V	
Gate-Source Voltage	V <sub>GSS</sub>	±20	V	
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	I <sub>D</sub>	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	-36 -29	A
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V		T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	-31 -25	A
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	I <sub>D</sub>	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	-14.5 -11.5	A
Pulsed Drain Current (Notes 5 & 8)		I <sub>DM</sub>	-100	A
Avalanche Current (Notes 9 & 10)	I <sub>AR</sub>	-17.5	A	
Repetitive Avalanche Energy (Notes 9 & 10) L = 1mH	E <sub>AR</sub>	153	mJ	

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	2.18	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C (Note 5)	R <sub>θJA</sub>	55	°C/W
Power Dissipation (Note 6)	P <sub>D</sub>	14.37	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C (Note 6)	R <sub>θJA</sub>	8.7	°C/W
Power Dissipation (Notes 6 & 7)	P <sub>D</sub>	58.7	W
Thermal Resistance, Junction to Case @T <sub>C</sub> = +25°C (Notes 6 & 7)	R <sub>θJC</sub>	2.13	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 10)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	-	-	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	-1.0	μA	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 10)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-1.1	-1.6	-2.1	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	-	5.7	7.5	mΩ	V <sub>GS</sub> = -10V, I <sub>D</sub> = -10A
		-	7.2	10		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -10A
Forward Transfer Admittance	Y <sub>fs</sub>	-	30	-	S	V <sub>DS</sub> = -15V, I <sub>D</sub> = -10A
Diode Forward Voltage	V <sub>SD</sub>	-	-0.65	-1.0	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A
<b>DYNAMIC CHARACTERISTICS (Note 11)</b>						
Input Capacitance	C <sub>iss</sub>	-	6234	-	pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	-	1500	-	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	-	774	-	pF	
Gate Resistance	R <sub>g</sub>	-	1.28	-	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge (V <sub>GS</sub> = -10V)	Q <sub>g</sub>	-	126.2	-	nC	V <sub>DS</sub> = -15V, I <sub>D</sub> = -10A
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Q <sub>g</sub>	-	59.2	-	nC	V <sub>DS</sub> = -15V, V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -10A
Gate-Source Charge	Q <sub>gs</sub>	-	16.1	-	nC	
Gate-Drain Charge	Q <sub>gd</sub>	-	15.7	-	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	-	11.4	-	ns	V <sub>DS</sub> = -15V, V <sub>GEN</sub> = -10V, R <sub>G</sub> = 6Ω, I <sub>D</sub> = -1A
Turn-On Rise Time	t <sub>r</sub>	-	9.4	-	ns	
Turn-Off Delay Time	t <sub>D(off)</sub>	-	260.7	-	ns	
Turn-Off Fall Time	t <sub>f</sub>	-	99.3	-	ns	

- Notes:
- Device mounted on FR-4 PCB with 1 inch square 2 oz. Copper, single sided.
  - Device mounted on FR-4 PCB with infinite heatsink.
  - R<sub>θJC</sub> is guaranteed by design while R<sub>θCA</sub> is determined by the user's board design.
  - Repetitive rating, pulse width limited by junction temperature, 10μs pulse, duty cycle = 1%.
  - I<sub>AR</sub> and E<sub>AR</sub> rating are based on low frequency and duty cycles to keep T<sub>J</sub> = 25°C
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to production testing.

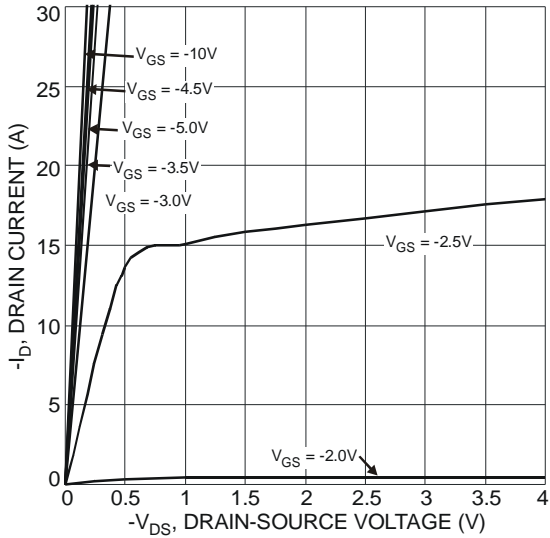


Fig. 1 Typical Output Characteristic

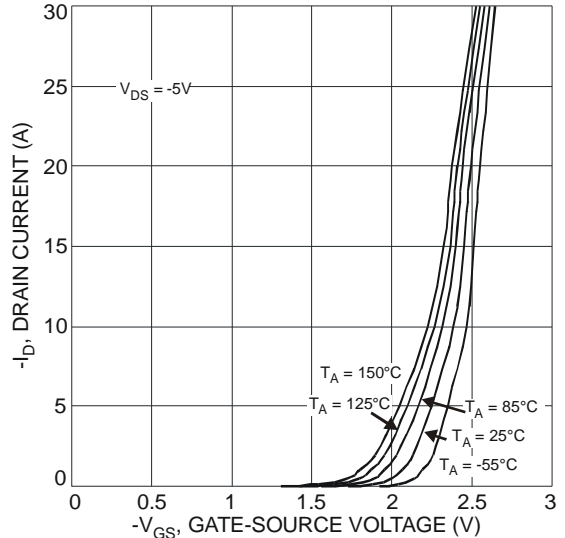


Fig. 2 Typical Transfer Characteristic

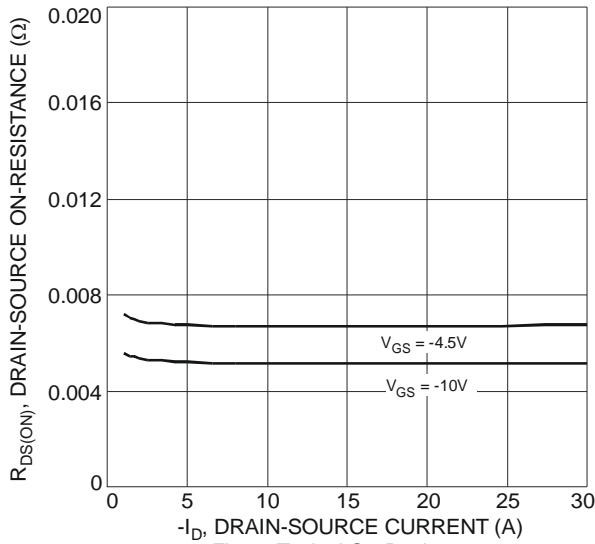


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

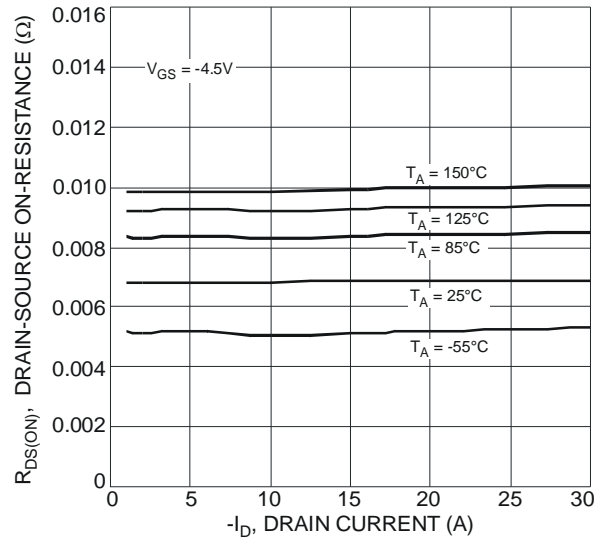


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

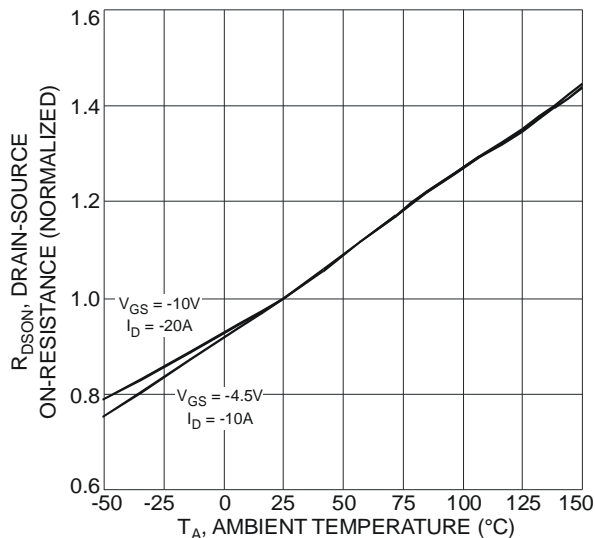


Fig. 5 On-Resistance Variation with Temperature

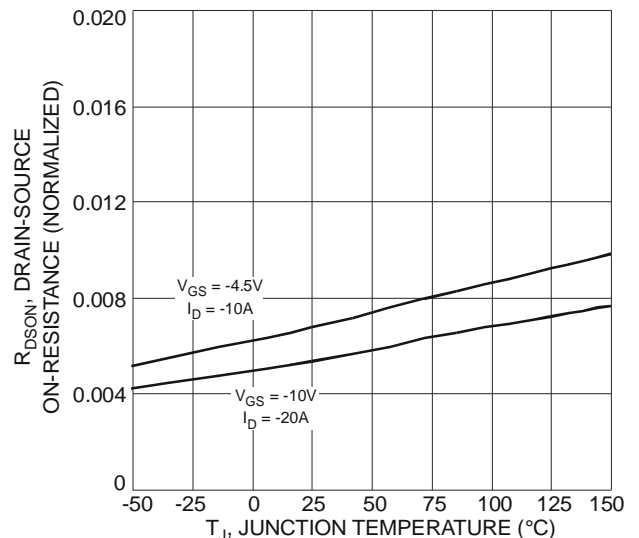


Fig. 6 On-Resistance Variation with Temperature

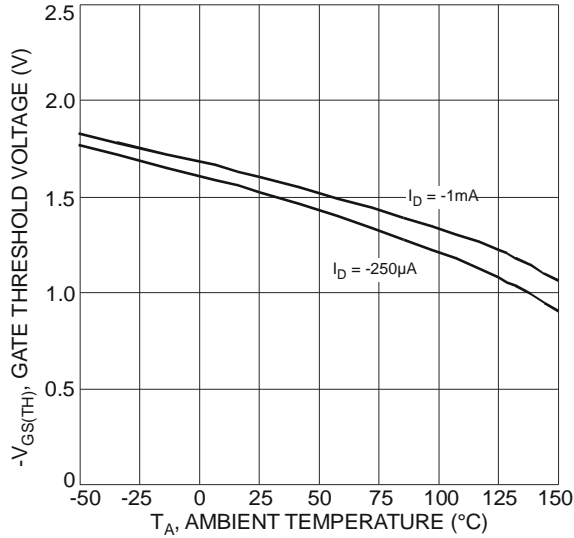


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

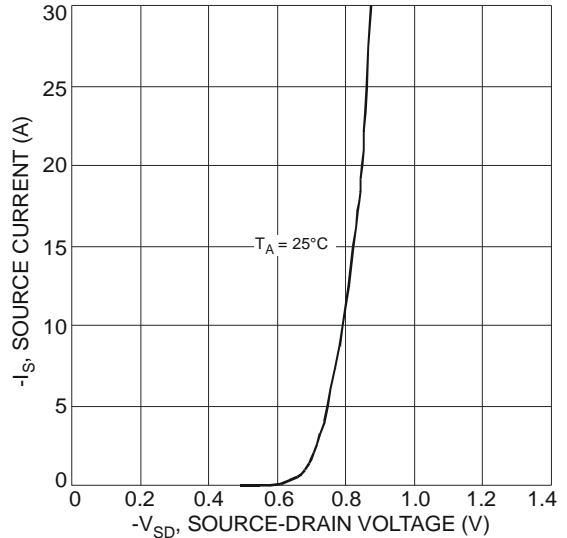


Fig. 8 Diode Forward Voltage vs. Current

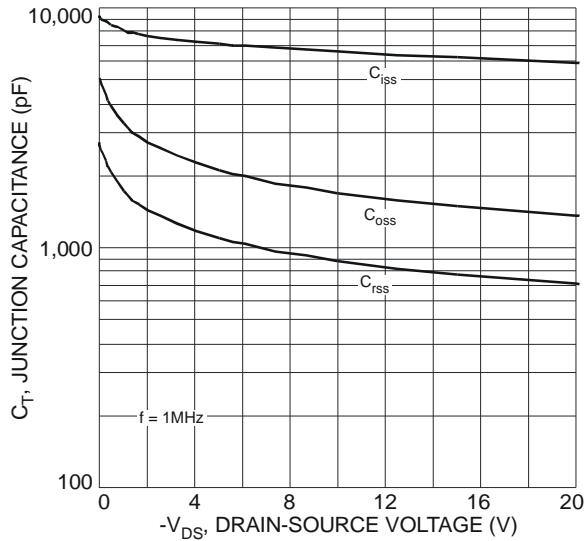


Fig. 9 Typical Total Capacitance

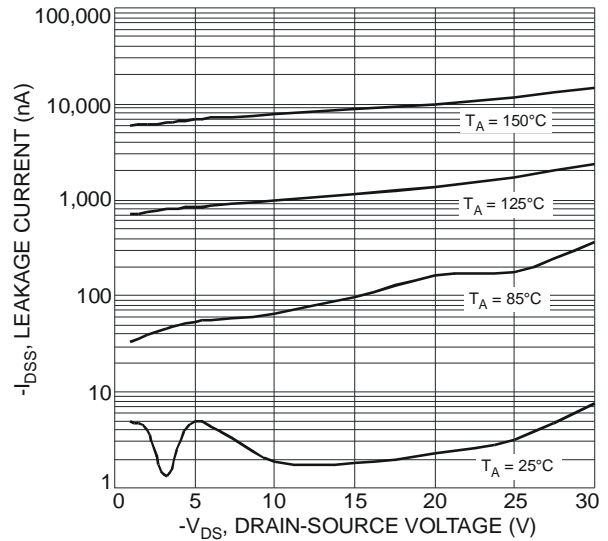


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

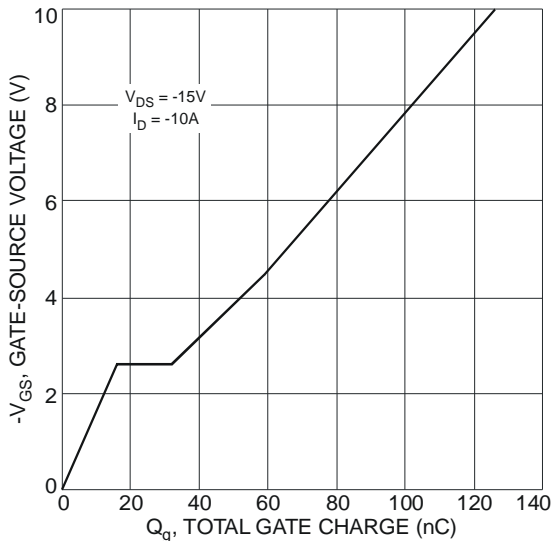


Fig. 11 Gate-Source Voltage vs. Total Gate Charge

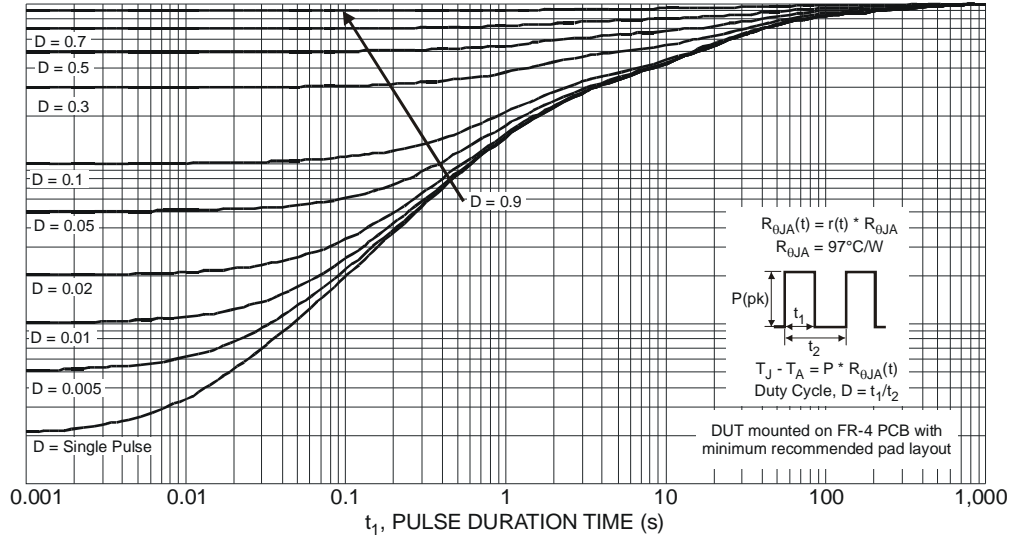
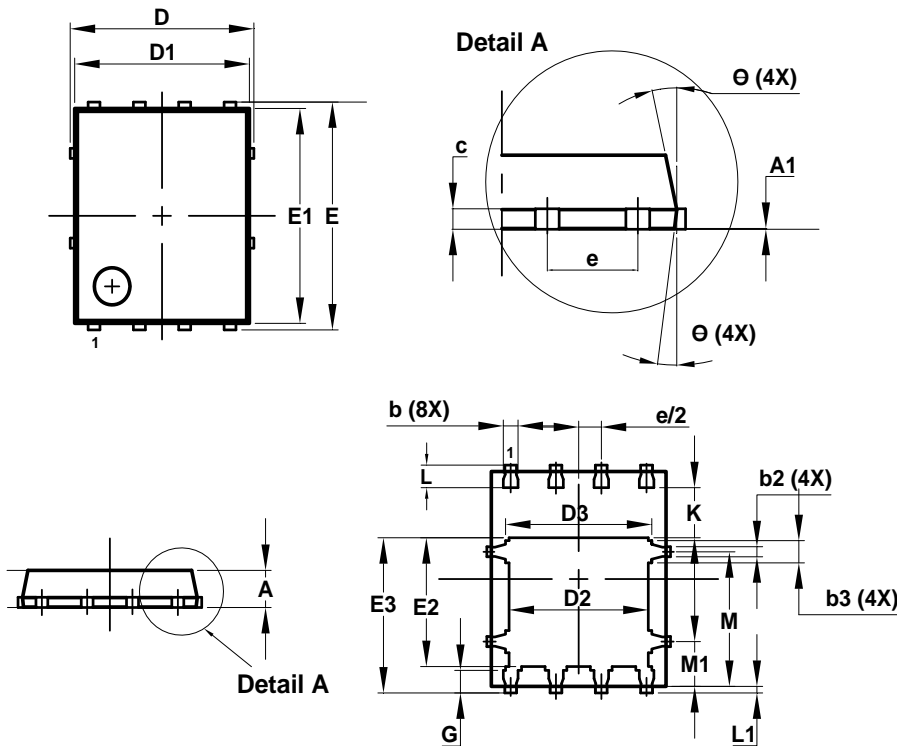


Fig. 12 Transient Thermal Response

**Package Outline Dimensions**

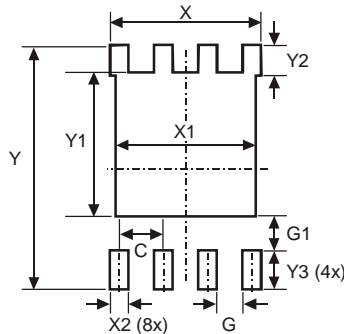
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



POWERDI5060-8			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	—
b	0.33	0.51	0.41
b2	0.200	0.350	0.273
b3	0.40	0.80	0.60
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.70	4.10	3.90
D3	3.90	4.30	4.10
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	3.28	3.68	3.48
E3	3.99	4.39	4.19
e	1.27 BSC		
G	0.51	0.71	0.61
K	0.51	—	—
L	0.51	0.71	0.61
L1	0.050	0.20	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
theta	10°	12°	11°
theta1	6°	8°	7°
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	4.420
X1	4.100
X2	0.610
Y	6.610
Y1	3.810
Y2	1.020
Y3	1.270

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